

ABSTRACT

An electroplating apparatus proposed in this invention comprises a central flow tube, and the central flow tube is inserted through an anode. One end of the central flow tube serves as an anode electroplating solution inlet, and the other end extends out of the anode surface and is connected to a plurality of branch flow tubes extending toward the anode edge. Each branch flow tube is provided with a plurality of spray holes; the anode electroplating solution is supplied to the anode surface through the spray holes of the branch flow tubes. This electroplating apparatus can guide the anode electroplating solution to the anode surface, and use the impact force of the solution to timely wash away the oxides generated on the anode surface, thereby ensuring that the circuit impedance remains unchanged and avoiding the increase of the circuit voltage. In addition, the fluidity of the anode electroplating solution and the uniformity of the flow rate can be enhanced.